

MATERIAL DECLARATION SHEET



Package Type	TBU-P40		
Product Line	Semiconductor Products		
Compliance Date	January 1, 2008		
RoHS Compliant	Yes	MSL	1

No.	Construction Element (Subpart)	Homogeneous Material	Material Weight [g]	Homogeneous Material\ Substances	CAS Number if applicable	Materials Mass %	Material Mass % of Total Unit Weight	Subpart Mass of Total Wt. (%)
1	Encapsulation	Epoxy resin	0.01993	Epoxy Resin	Trade Secret	6	2.7732	46.220
				Phenol Resin	Trade Secret	3	1.3866	
				Silica fused	60676-86-0	90.45	41.8059	
				Carbon Black	1333-86-4	0.55	0.2542	
2	Leadframe	Copper alloy	0.01833	Copper	7440-50-8	96	40.8089	42.509
				Iron	7439-89-6	2.2	0.9352	
				Zinc	7440-66-6	0.1	0.0425	
				Phosphorous	7723-14-0	0.075	0.0319	
				Lead (impurity)	7439-92-1	0.001	0.0004	
				Silver (Plating)	7440-22-4	1.624	06903	
3	Chip	Silicon	0.00205	Silicon	7440-21-3	100	4.7542	4.754
4	Die Attach	Conductive Silver Epoxy	0.00136	Silver	7440-22-4	93.4	2.9458	3.154
				Epoxy resin	Trade Secret	5.5	0.1735	
				Polymeric compound	Trade Secret	0.55	0.0173	
				Functionalized Ester	Trade Secret	0.55	0.0173	
5	Bond wires	Gold	0.00009	Gold	7440-57-5	99.99	0.2087	0.209
				Potential impurities may include Ag, Be or Ca ≤ 30 ppm	7440-22-4; 7440-41-7; 7440-70-2	0.01	0.0003	

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6	Terminal Finish	Alloy	0.00136	Tin	7440-31-5	100.00	3.154	3.154
		Total Weight	0.04312					

Updated January 29, 2019